

# QSB363C

## Subminiature Plastic Silicon Infrared Phototransistor

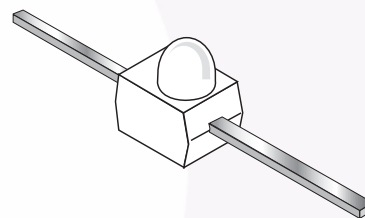
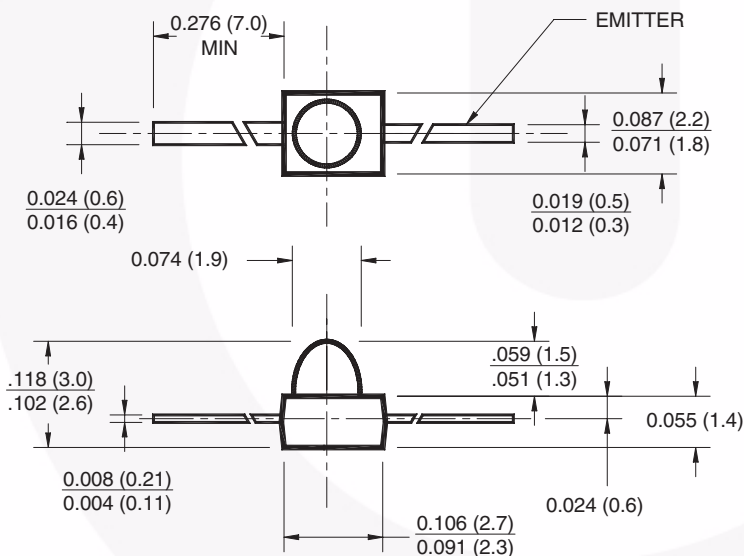
### Features

- NPN Silicon Phototransistor
- T-3/4 (2mm) Surface Mount Package
- Medium Wide Beam Angle, 24°
- Clear Plastic Package
- Matched Emitters: QEB363 or QEB373
- Tape & Reel Option (See Tape & Reel Specifications)
- Lead Form Options: Gullwing, Yoke, Z-Bend

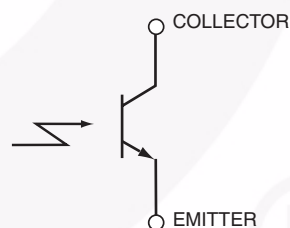
### Description

The QSB363 is a silicon phototransistor encapsulated in a clear infrared T-3/4 package.

### Package Dimensions



### Schematic



### NOTES:

1. Dimensions are in inches (mm).
2. Tolerance of  $\pm .010$  (.25) on all non nominal dimensions unless otherwise specified.

### Absolute Maximum Ratings ( $T_A = 25^\circ\text{C}$ unless otherwise specified)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. )

Symbol	Parameter	Rating	Unit
$T_{OPR}$	Operating Temperature	-25 to +85	$^\circ\text{C}$
$T_{STG}$	Storage Temperature	-40 to +85	$^\circ\text{C}$
$T_{SOL}$	Soldering Temperature (Iron) <sup>(2,3,4)</sup>	260	$^\circ\text{C}$
$T_{SOL}$	Soldering Temperature (Flow) <sup>(2,3)</sup>	260	$^\circ\text{C}$
$V_{CEO}$	Collector Emitter Voltage	30	V
$V_{ECO}$	Emitter Collector Voltage	5	V
$P_C$	Power Dissipation <sup>(1)</sup>	75	mW

#### Notes

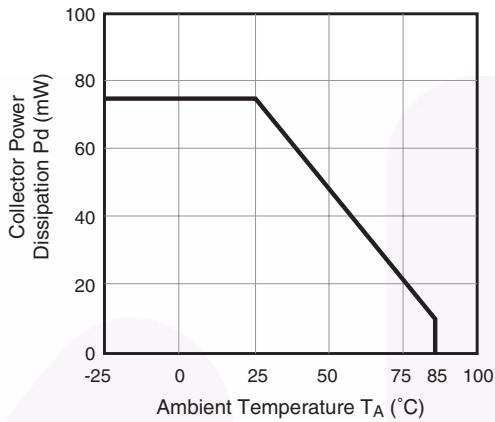
- Derate power dissipation linearly 1.33mW/ $^\circ\text{C}$  above 25 $^\circ\text{C}$ .
- RMA flux is recommended.
- Methanol or isopropyl alcohols are recommended as cleaning agents.
- Pulse conditions:  $t_p = 100\mu\text{s}$ ,  $T = 10\text{ms}$ .
- D = 940nm, GaAs.

### Electrical/Optical Characteristics ( $T_A = 25^\circ\text{C}$ )

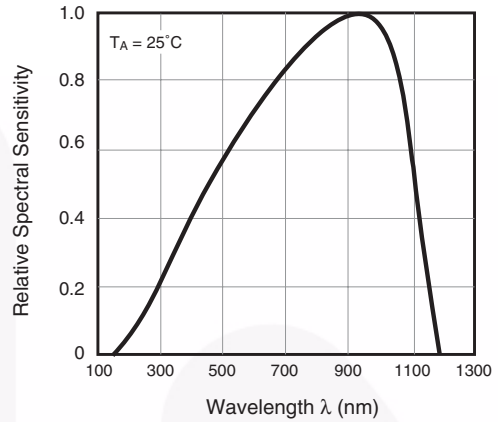
Symbol	Parameters	Test Conditions	Min.	Typ.	Max.	Units
$\lambda_P$	Peak Sensitivity Wavelength			940		nm
$\Theta$	Reception Angle			$\pm 12$		
$I_{CEO}$	Collector Dark Current	$V_{CE} = 20\text{V}$ , $E_e = 0\text{mW}/\text{cm}^2$			100	nA
$BV_{CEO}$	Collector-Emitter Breakdown Voltage	$I_C = 100\mu\text{A}$ , $E_e = 0\text{mW}/\text{cm}^2$	30			V
$BV_{ECO}$	Emitter-Collector Breakdown Voltage	$I_E = 100\mu\text{A}$ , $E_e = 0\text{mW}/\text{cm}^2$	5			V
$I_{C(on)}$	On-State Collector Current	$V_{CE} = 5\text{V}$ , $E_e = 0.5\text{mW}/\text{cm}^2$	1.0	1.5		mA
$V_{CE(SAT)}$	Collector-Emitter Saturation Voltage	$I_C = 2\text{mA}$ , $E_e = 1\text{mW}/\text{cm}^2$			0.4	V
$t_r$	Rise Time	$V_{CE} = 5\text{V}$ , $I_C = 1\text{mA}$ , $R_L = 1000\Omega$		15		$\mu\text{s}$
$t_f$	Fall Time			15		$\mu\text{s}$

## Typical Performance Curves

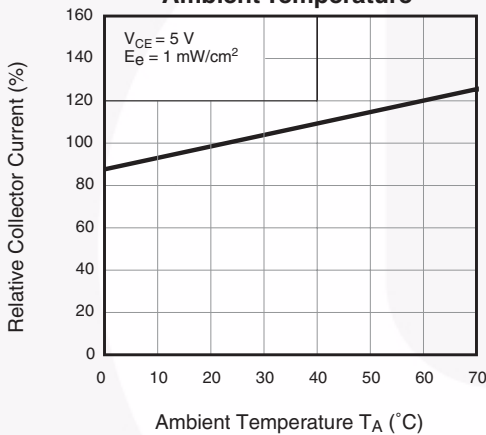
**Fig. 1 Collector Power Dissipation vs. Ambient Temperature**



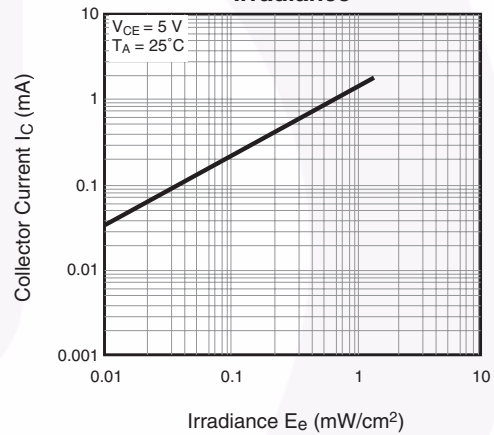
**Fig. 2 Spectral Sensitivity**



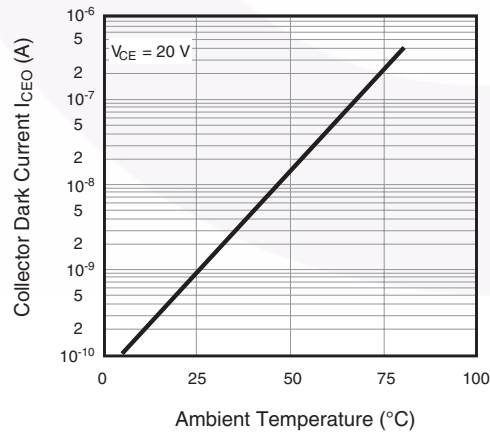
**Fig. 3 Relative Collector Current vs. Ambient Temperature**



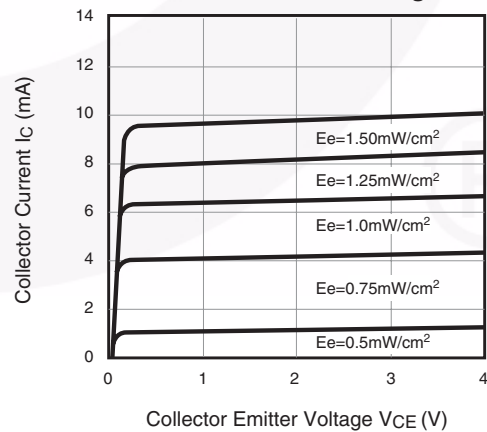
**Fig. 4 Collector Current vs. Irradiance**



**Fig. 5 Collector Dark Current vs. Ambient Temperature**



**Fig. 6 Collector Current vs. Collector Emitter Voltage**

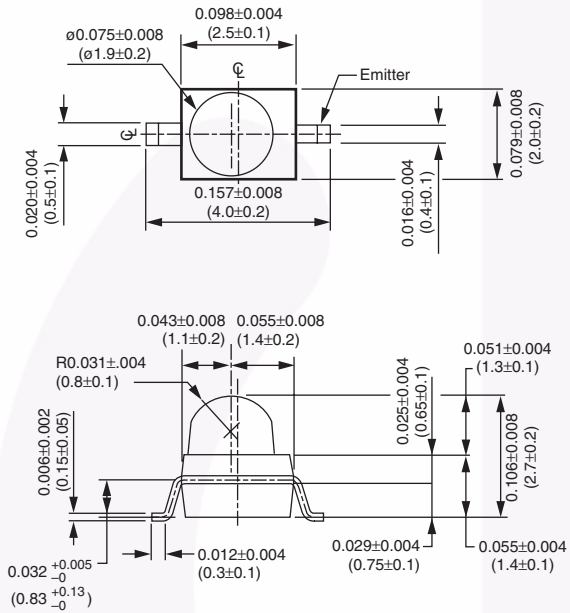


## Package Dimensions

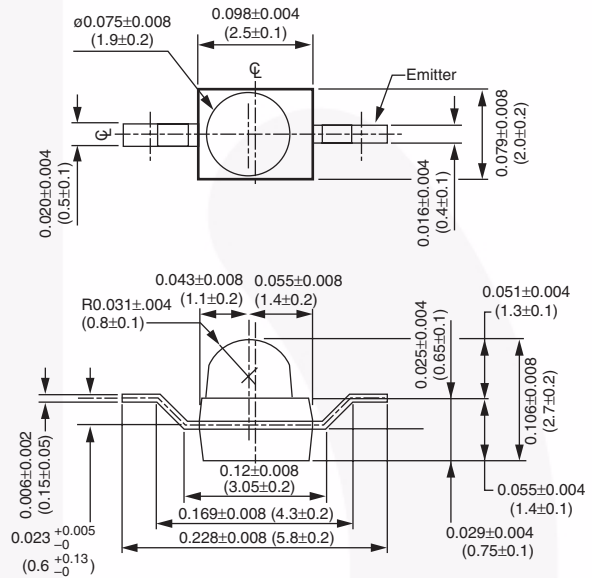
### Features

- Three lead forming options: Gull Wing, Yoke and Z-Bend
- Compatible with automatic placement equipment
- Supplied on tape and reel or in bulk packaging
- Compatible with vapor phase reflow solder processes

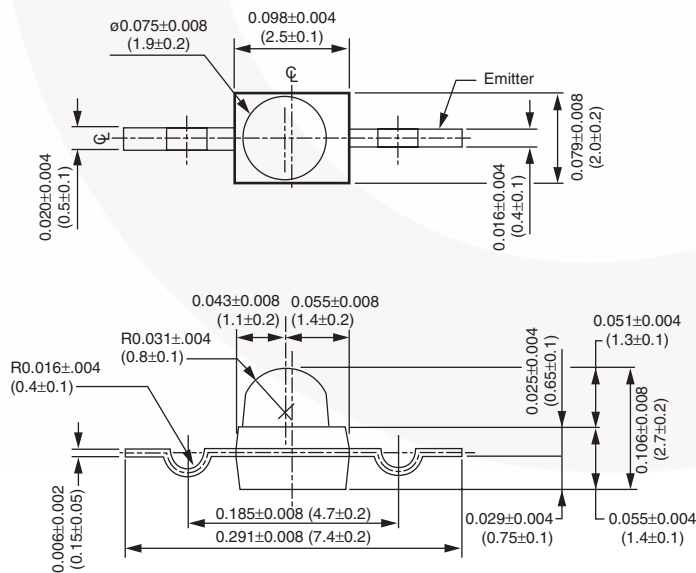
### Gull Wing Lead Configuration



### Z-Bend Lead Configuration





### Yoke Lead Configuration





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